

Tyrone Camarero Specifications

Tyrone

Camerero: SDI200A2G-1010

Key Feature

DP Intel 10U System with NVIDIA HGX B200 8-GPU

Scientific Research, Conversational AI Business Intelligence & Analytics, Drug Discovery, Finance Services and Fraud Detection, AI/Deep Learning Training and Inference Large Language Model (LLM) and Generative AI, High Performance Computing (HPC) Autonomous Vehicle Technologies

- Dual Socket E (LGA-4677), 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors
- 8x NVIDIA B200 SXM GPUs, 1.4TB HBM3e GPU Memory Space
- 32x DIMM slots, DDR5 up to 5600MT/s(1DPC), 4800MT/s(2DPC)
- 8x PCIe 5.0 x16 LP, 2x PCIe 5.0 x16 FHHL slots
- 10x Front Hot-swap 2.5" NVMe U.2 , 2x NVMe M.2
- 2x 10GbE RJ-45, 1x Dedicated BMC/IPMI
- 15 heavy duty hot-swappable 80mm Fan(s), 4 heavy duty internal 60mm Fan(s)
- 6x 5250W Redundant (3+3) Power Supplies Titanium Level Efficiency



Processor/Cache		Front Panel	
Processor	Dual Socket E (LGA-4677), 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors	LED	HDD activity, Network activity LEDs, System information (overheat/UID) , UID
Chipset		Buttons	Power On/Off button,UID/ Reset button
Chipset	System on Chip	Drive bays	
System Memory		HDD Bays	10 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bays, 2 M.2 PCIe 3.0 x4 NVMe slots
Memory Capacity	32 DIMM slots Max Memory (1DPC): Up to 4TB 5600MT/s ECC DDR5 RDIMM, Max Memory (2DPC): Up to 8TB 4400MT/s ECC DDR5 RDIMM	Power Supply	
Expansion Slot		Power Supply	6x 5250W Redundant (3 + 3) Titanium Level (96%) Hot-plug power supplies
PCI-Express	8 PCIe 5.0 x16 LP slots, 2 PCIe 5.0 x16 FHHL slots	Cooling System	
Integrated Onboard		Cooling System	15 heavy duty hot-swappable 80mm Fan(s), 4 heavy duty internal 60mm Fan(s)
GPU	8 onboard GPUs	Form Factor	
Network Connectivity	2 RJ45 10GbE	Form Factor	10U Rackmount
Add-on Options		Dimensions	
Raid Card	None	Dimensions	Height : 17.2" (438.8 mm), Width-17.6" (449 mm), Depth -33.2" (843.28 mm)
Optical Drive	None	Email : Info@tyronesystems.com For more/current product information, Visit www.tyronesystems.com	

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